

**QFN Packaged, +/-15kV ESD Protected, +2.7V to +5.5V, 150Nanoamp, 250kBps, RS-232 Transmitters/Receivers**

The Intersil ISL422XE devices are 2.7V to 5.5V powered RS-232 transmitters/receivers which meet EIA/TIA-232 and V.28/V.24 specifications, even at  $V_{CC} = 3.0V$ . Additionally, they provide  $\pm 15kV$  ESD protection (IEC61000-4-2 Air Gap, and Human Body Model) on transmitter outputs and receiver inputs (RS-232 pins). Targeted applications are PDAs, Palmtops, and hand-held products where the low operational, and even lower standby, power consumption is critical. Efficient on-chip charge pumps, coupled with manual and automatic powerdown functions, reduce the standby supply current to a 150nA trickle. Tiny 5mm x 5mm **Quad Flat No-Lead** (QFN) packaging and the use of small, low value capacitors ensure board space savings as well. Data rates greater than 250kBps are guaranteed at worst case load conditions.

The ISL4221E is a 1 driver, 1 receiver device and the ISL4223E is a 2 driver, 2 receiver device that, coupled with the 5x5 QFN package, provide the industry's smallest, lowest power serial port suitable for PDAs, and hand-held applications. The 5x5 QFN requires 40% less board area than a 20 lead TSSOP, and is nearly 20% thinner.

The **ISL422XE** features an **automatic powerdown** function that powers down the on-chip power-supply and driver circuits. This occurs when an attached peripheral device is shut off or the RS-232 cable is removed, conserving system power automatically without changes to the hardware or operating system. It powers up again when a valid RS-232 voltage is applied to any receiver input.

Table 1 summarizes the features of the ISL422XE, while Application Note AN9863 summarizes the features of each device comprising the 3V RS-232 family.

**Features**

- Available in Near Chip Scale QFN (5mmx5mm) Package which is 40% Smaller than a 20 Lead TSSOP
- ESD Protection for RS-232 I/O Pins to  $\pm 15kV$  (IEC61000)
- Meets EIA/TIA-232 and V.28/V.24 Specifications at 3V
- RS-232 Compatible with  $V_{CC} = 2.7V$
- On-Chip Voltage Converters Require Only Four External 0.1 $\mu F$  Capacitors
- Manual and Automatic Powerdown Features
- Receiver Hysteresis For Improved Noise Immunity
- Guaranteed Minimum Data Rate . . . . . 250kBps
- Wide Power Supply Range. . . . . Single +2.7V to +5.5V
- Low Supply Current in Powerdown State . . . . . 150nA
- Pb-free Available as an Option

**Applications**

- Any Space Constrained System Requiring RS-232 Ports
  - Battery Powered, and Portable Equipment
  - Hand-Held Products (GPS Receivers, Bar Code Scanners, etc.)
  - PDAs and Palmtops, Data Cables
  - Cellular/Mobile Phones, Digital Cameras

**Related Literature**

- Technical Brief TB363 "Guidelines for Handling and Processing Moisture Sensitive Surface Mount Devices"
- "Technical Brief TB379 "Thermal Characterization of Packages for ICs"
- Technical Brief TB389 "PCB Land Pattern Design and Surface Mount Guidelines for QFN Packages"

**TABLE 1. SUMMARY OF FEATURES**

PART NUMBER	NO. OF Tx.	NO. OF Rx.	QFN PKG. AVAILABLE?	DATA RATE (kBps)	Rx. ENABLE FUNCTION?	MANUAL POWERDOWN?	AUTOMATIC POWERDOWN FUNCTION?
ISL4221E	1	1	YES	250	YES	YES	YES
ISL4223E	2	2	YES	250	YES	YES	YES

**Ordering Information**

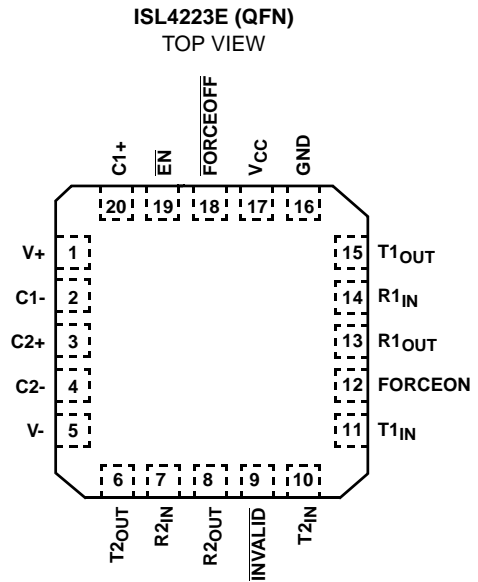
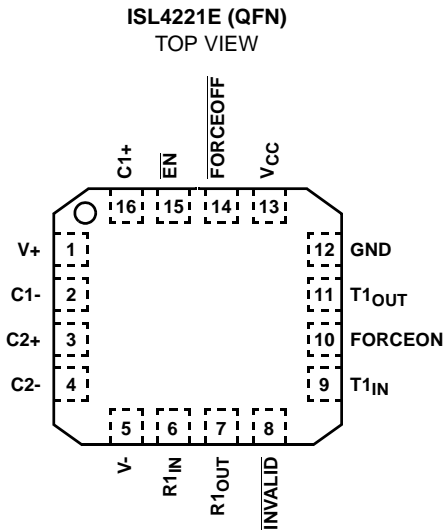
PART NO.	TEMP. RANGE (°C)	PACKAGE	PKG. DWG. #
ISL4221EIR	-40 to 85	16 Ld QFN	L16.5x5
ISL4221EIR-T	-40 to 85	16 Ld QFN Tape & Reel	L16.5x5
ISL4221EIRZ-T (Note)	-40 to 85	16 Ld QFN Tape & Reel (Pb-free)	L16.5x5
ISL4223EIR	-40 to 85	20 Ld QFN	L20.5x5
ISL4223EIRZ (Note)	-40 to 85	20 Ld QFN (Pb-free)	L20.5x5

**Ordering Information (Continued)**

PART NO.	TEMP. RANGE (°C)	PACKAGE	PKG. DWG. #
ISL4223EIR-T	-40 to 85	20 Ld QFN Tape & Reel	L20.5x5
ISL4223EIRZ-T (Note)	-40 to 85	20 Ld QFN Tape & Reel (Pb-free)	L20.5x5

NOTE: Intersil Pb-free products employ special Pb-free material sets; molding compounds/die attach materials and 100% matte tin plate termination finish, which is compatible with both SnPb and Pb-free soldering operations. Intersil Pb-free products are MSL classified at Pb-free peak reflow temperatures that meet or exceed the Pb-free requirements of IPC/JEDEC J Std-020B.

**Pinouts**

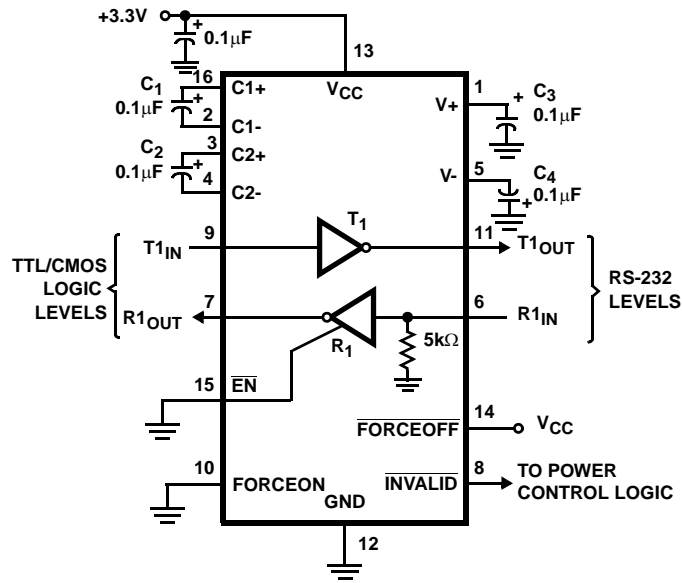


**Pin Descriptions**

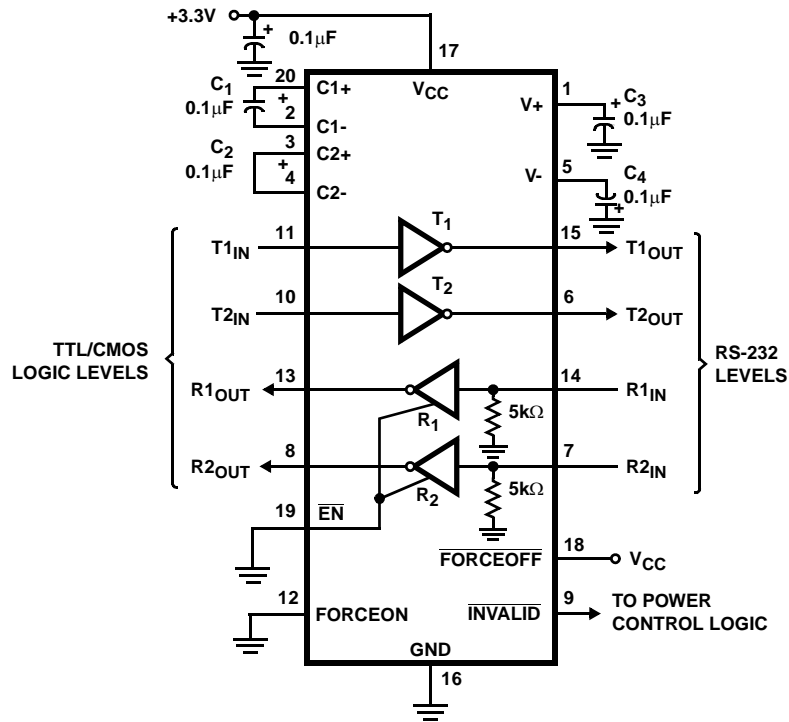
PIN	FUNCTION
V <sub>CC</sub>	System power supply input (2.7V to 5.5V).
V+	Internally generated positive transmitter supply (+5.5V).
V-	Internally generated negative transmitter supply (-5.5V).
GND	Ground connection.
C1+	External capacitor (voltage doubler) is connected to this lead.
C1-	External capacitor (voltage doubler) is connected to this lead.
C2+	External capacitor (voltage inverter) is connected to this lead.
C2-	External capacitor (voltage inverter) is connected to this lead.
T <sub>IN</sub>	TTL/CMOS compatible transmitter Inputs.
T <sub>OUT</sub>	±15kV ESD Protected, RS-232 level (nominally ±5.5V) transmitter outputs.
R <sub>IN</sub>	±15kV ESD Protected, RS-232 compatible receiver inputs.
R <sub>OUT</sub>	TTL/CMOS level receiver outputs.
INVALID	Active low output that indicates if no valid RS-232 levels are present on any receiver input.
FORCEOFF	Active low to shut down transmitters and on-chip power supply. This overrides any automatic circuitry and FORCEON (see Table 2).
FORCEON	Active high input to override automatic powerdown circuitry thereby keeping transmitters active. (FORCEOFF must be high).
EN	Active low receiver enable control.

Typical Operating Circuits

ISL4221E



ISL4223E



# ISL4221E, ISL4223E

## Absolute Maximum Ratings

V <sub>CC</sub> to Ground	-0.3V to 6V
V <sub>+</sub> to Ground	-0.3V to 7V
V <sub>-</sub> to Ground	+0.3V to -7V
V <sub>+</sub> to V <sub>-</sub>	14V
Input Voltages	
T <sub>IN</sub> , FORCEOFF, FORCEON, EN	-0.3V to 6V
R <sub>IN</sub>	±25V
Output Voltages	
T <sub>OUT</sub>	±13.2V
R <sub>OUT</sub> , INVALID	-0.3V to V <sub>CC</sub> +0.3V
Short Circuit Duration	
T <sub>OUT</sub>	Continuous
ESD Rating	See Specification Table

## Thermal Information

Thermal Resistance (Typical, Note 1)	θ <sub>JA</sub> (°C/W)
16 Ld QFN Package	35
20 Ld QFN Package	32
Moisture Sensitivity (see Technical Brief TB363)	
QFN Package	Level 1
Maximum Junction Temperature (Plastic Package)	150°C
Maximum Storage Temperature Range	-65°C to 150°C
Maximum Lead Temperature (Soldering 10s)	300°C

## Operating Conditions

Temperature Range	
ISL422XEIR	-40°C to 85°C

**CAUTION:** Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

### NOTE:

1. θ<sub>JA</sub> is measured in free air with the component mounted on a high effective thermal conductivity test board with "direct attach" features. See Tech Brief TB379, and Tech Brief TB389.

**Electrical Specifications** Test Conditions: V<sub>CC</sub> = 3V to 5.5V, C<sub>1</sub> - C<sub>4</sub> = 0.1µF; Unless Otherwise Specified.  
Typicals are at T<sub>A</sub> = 25°C

PARAMETER	TEST CONDITIONS	TEMP (°C)	MIN	TYP	MAX	UNITS
<b>DC CHARACTERISTICS</b>						
Supply Current, Automatic Powerdown	All R <sub>IN</sub> Open, FORCEON = GND, FORCEOFF = V <sub>CC</sub>	25	-	0.15	1	µA
Supply Current, Powerdown	FORCEOFF = GND	25	-	0.15	1	µA
Supply Current, Automatic Powerdown Disabled	All Outputs Unloaded, FORCEON = FORCEOFF = V <sub>CC</sub>	25	-	0.3	1.0	mA
<b>LOGIC AND TRANSMITTER INPUTS AND RECEIVER OUTPUTS</b>						
Input Logic Threshold Low	T <sub>IN</sub> , FORCEON, FORCEOFF, EN	Full	-	-	0.8	V
Input Logic Threshold High	T <sub>IN</sub> , FORCEON, FORCEOFF, EN	V <sub>CC</sub> = 3.3V	Full	2.0	-	V
		V <sub>CC</sub> = 5.0V	Full	2.4	-	V
Input Leakage Current	T <sub>IN</sub> , FORCEON, FORCEOFF, EN	Full	-	±0.01	±1.0	µA
Output Leakage Current	EN = V <sub>CC</sub>	Full	-	±0.05	±10	µA
Output Voltage Low	I <sub>OUT</sub> = 1.6mA	Full	-	-	0.4	V
Output Voltage High	I <sub>OUT</sub> = -1.0mA	Full	V <sub>CC</sub> -0.6	V <sub>CC</sub> -0.1	-	V
<b>AUTOMATIC POWERDOWN (FORCEON = GND, FORCEOFF = V<sub>CC</sub>)</b>						
Receiver Input Thresholds to Enable Transmitters	ISL422XE Powers Up (See Figure 6)	Full	-2.7	-	2.7	V
Receiver Input Thresholds to Disable Transmitters	ISL422XE Powers Down (See Figure 6)	Full	-0.3	-	0.3	V
INVALID Output Voltage Low	I <sub>OUT</sub> = 1.6mA	Full	-	-	0.4	V
INVALID Output Voltage High	I <sub>OUT</sub> = -1.0mA	Full	V <sub>CC</sub> -0.6	-	-	V
Receiver Threshold to Transmitters Enabled Delay (t <sub>WU</sub> )		25	-	100	-	µs
Receiver Positive or Negative Threshold to INVALID High Delay (t <sub>INVH</sub> )		25	-	1	-	µs
Receiver Positive or Negative Threshold to INVALID Low Delay (t <sub>INVL</sub> )		25	-	30	-	µs

# ISL4221E, ISL4223E

**Electrical Specifications** Test Conditions:  $V_{CC} = 3V$  to  $5.5V$ ,  $C_1 - C_4 = 0.1\mu F$ ; Unless Otherwise Specified.  
Typicals are at  $T_A = 25^\circ C$  (Continued)

PARAMETER	TEST CONDITIONS	TEMP (°C)	MIN	TYP	MAX	UNITS	
<b>RECEIVER INPUTS</b>							
Input Voltage Range		25	-25	-	25	V	
Input Threshold Low	$V_{CC} = 3.3V$	25	0.6	1.2	-	V	
	$V_{CC} = 5.0V$	25	0.8	1.5	-	V	
Input Threshold High	$V_{CC} = 3.3V$	25	-	1.5	2.4	V	
	$V_{CC} = 5.0V$	25	-	1.8	2.4	V	
Input Hysteresis		25	-	0.5	-	V	
Input Resistance		25	3	5	7	k $\Omega$	
<b>TRANSMITTER OUTPUTS</b>							
Output Voltage Swing	All Transmitter Outputs Loaded with 3k $\Omega$ to Ground	Full	$\pm 5.0$	$\pm 5.4$	-	V	
Output Resistance	$V_{CC} = V_+ = V_- = 0V$ , Transmitter Output = $\pm 2V$	Full	300	10M	-	$\Omega$	
Output Short-Circuit Current		Full	-	$\pm 35$	$\pm 60$	mA	
Output Leakage Current	$V_{OUT} = \pm 12V$ , $V_{CC} = 0V$ or $3V$ to $5.5V$ , Automatic Powerdown or $\overline{FORCEOFF} = GND$	Full	-	-	$\pm 25$	$\mu A$	
<b>TIMING CHARACTERISTICS</b>							
Maximum Data Rate	$R_L = 3k\Omega$ , $C_L = 1000pF$ , One Transmitter Switching	Full	250	500	-	kBps	
Receiver Propagation Delay	Receiver Input to Receiver Output, $C_L = 150pF$	$t_{PHL}$	25	-	0.15	-	$\mu s$
		$t_{PLH}$	25	-	0.15	-	$\mu s$
Receiver Output Enable Time	Normal Operation	25	-	200	-	ns	
Receiver Output Disable Time	Normal Operation	25	-	200	-	ns	
Transmitter Skew	$t_{PHL} - t_{PLH}$ (Note 2)	25	-	100	-	ns	
Receiver Skew	$t_{PHL} - t_{PLH}$	25	-	50	-	ns	
Transition Region Slew Rate	$V_{CC} = 3.3V$ , $R_L = 3k\Omega$ to $7k\Omega$ , Measured From $3V$ to $-3V$ or $-3V$ to $3V$	$C_L = 150pF$ to $2500pF$	25	4	-	30	V/ $\mu s$
		$C_L = 150pF$ to $1000pF$	25	6	-	30	V/ $\mu s$
<b>ESD PERFORMANCE</b>							
RS-232 Pins ( $T_{OUT}$ , $R_{IN}$ )	Human Body Model	25	-	$\pm 15$	-	kV	
	IEC61000-4-2 Contact Discharge	25	-	$\pm 8$	-	kV	
	IEC61000-4-2 Air Gap Discharge	25	-	$\pm 15$	-	kV	
All Other Pins	Human Body Model	25	-	$\pm 2$	-	kV	

NOTE:

- Transmitter skew is measured at the transmitter zero crossing points.

## Detailed Description

The ISL422XE operate from a single +2.7V to +5.5V supply, guarantee a 250kBps minimum data rate, require only four small external 0.1 $\mu F$  capacitors, feature low power consumption, and meet all EIA RS-232C and V.28 specifications even with  $V_{CC} = 3.0V$ . The circuit is divided into three sections: The charge pump, the transmitters, and the receivers.

## Charge-Pump

Intersil's new ISL422XE devices utilize regulated on-chip dual charge pumps as voltage doublers, and voltage inverters to generate  $\pm 5.5V$  transmitter supplies from a  $V_{CC}$  supply as low as 3.0V. This allows them to maintain RS-232 compliant output levels over the  $\pm 10\%$  tolerance range of 3.3V powered systems. The efficient on-chip power supplies require only four small, external 0.1 $\mu F$  capacitors for the voltage doubler and inverter functions. The charge pumps operate discontinuously (i.e., they turn off as soon as the  $V_+$

and V- supplies are pumped up to the nominal values), resulting in significant power savings.

**Transmitters**

The transmitters are proprietary, low dropout, inverting drivers that translate TTL/CMOS inputs to EIA/TIA-232 output levels. Coupled with the on-chip ±5.5V supplies, these transmitters deliver true RS-232 levels over a wide range of single supply system voltages.

All transmitter outputs disable and assume a high impedance state when the device enters the powerdown mode (see Table 2). These outputs may be driven to ±12V when disabled.

The devices guarantee a 250kBps data rate for full load conditions (3kΩ and 1000pF), V<sub>CC</sub> ≥ 3.0V, with one transmitter operating at full speed. Under more typical conditions of V<sub>CC</sub> ≥ 3.3V, R<sub>L</sub> = 3kΩ, and C<sub>L</sub> = 250pF, one transmitter easily operates at 900kBps.

Transmitter inputs float if left unconnected, and may cause I<sub>CC</sub> increases. Connect unused inputs to GND for the best performance.

**Receivers**

All the ISL422XE devices contain standard inverting receivers that three-state via the  $\overline{EN}$  control line. All the receivers convert RS-232 signals to CMOS output levels and accept inputs up to ±25V while presenting the required 3kΩ to 7kΩ input impedance (see Figure 1) even if the power is off (V<sub>CC</sub> = 0V). The receivers' Schmitt trigger input stage uses hysteresis to increase noise immunity and decrease errors due to slow input signal transitions.

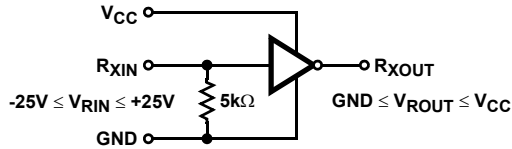


FIGURE 1. INVERTING RECEIVER CONNECTIONS

Receivers driving a powered down UART must be disabled to prevent current flow through, and possible damage to, the UART's protection diodes (see Figures 2 and 3). This can be accomplished on the ISL422XE by driving the  $\overline{EN}$  input high whenever the UART powers down. Figure 3 also shows that the  $\overline{INVALID}$  output can be used to determine when the UART should be powered down. When the RS-232 cable is disconnected,  $\overline{INVALID}$  switches low indicating that the UART is no longer needed. Reconnecting the cable drives  $\overline{INVALID}$  back high, indicating that the UART should be powered up.

**Low Power Operation**

These 3V devices require a nominal supply current of 0.3mA, even at V<sub>CC</sub> = 5.5V, during normal operation (not in powerdown mode). This is considerably less than the 5mA that

11mA current required by comparable 5V RS-232 devices, allowing users to reduce system power simply by switching to this new family.

**Powerdown Functionality**

The already low current requirement drops significantly when the device enters powerdown mode. In powerdown, supply current drops to 150nA, because the on-chip charge pump turns off (V+ collapses to V<sub>CC</sub>, V- collapses to GND), and the transmitter outputs three-state. Receiver outputs are unaffected by powerdown; refer to Table 2 for details. This micro-power mode makes the ISL422XE ideal for battery powered and portable applications.

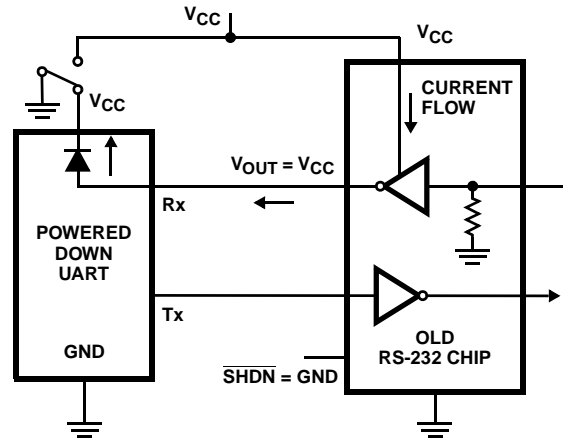


FIGURE 2. POWER DRAIN THROUGH POWERED DOWN PERIPHERAL

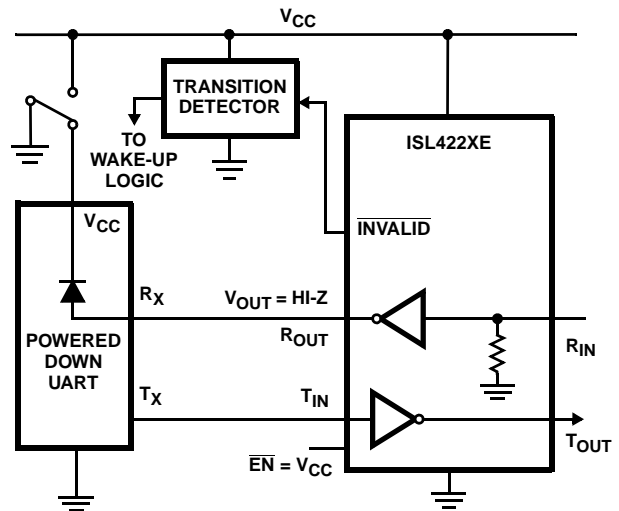


FIGURE 3. DISABLED RECEIVERS PREVENT POWER DRAIN

**Software Controlled (Manual) Powerdown**

The ISL422XE family provides pins that allow the user to force the IC into the low power, standby state.

The ISL422XE utilize a two pin approach where the FORCEON and FORCEOFF inputs determine the IC's

TABLE 2. POWERDOWN AND ENABLE LOGIC TRUTH TABLE

RS-232 SIGNAL PRESENT AT RECEIVER INPUT?	$\overline{\text{FORCEOFF}}$ INPUT	FORCEON INPUT	$\overline{\text{EN}}$ INPUT	TRANSMITTER OUTPUTS	RECEIVER OUTPUTS	$\overline{\text{INVALID}}$ OUTPUT	MODE OF OPERATION
NO	H	H	L	Active	Active	L	Normal Operation (Auto Powerdown Disabled)
NO	H	H	H	Active	High-Z	L	
YES	H	L	L	Active	Active	H	Normal Operation (Auto Powerdown Enabled)
YES	H	L	H	Active	High-Z	H	
NO	H	L	L	High-Z	Active	L	Powerdown Due to Auto Powerdown Logic
NO	H	L	H	High-Z	High-Z	L	
YES	L	X	L	High-Z	Active	H	Manual Powerdown
YES	L	X	H	High-Z	High-Z	H	Manual Powerdown w/Rcvr. Disabled
NO	L	X	L	High-Z	Active	L	Manual Powerdown
NO	L	X	H	High-Z	High-Z	L	Manual Powerdown w/Rcvr. Disabled

mode. For always enabled operation, FORCEON and  $\overline{\text{FORCEOFF}}$  are both strapped high. To switch between active and powerdown modes, under logic or software control, only the  $\overline{\text{FORCEOFF}}$  input need be driven. The FORCEON state isn't critical, as  $\overline{\text{FORCEOFF}}$  dominates over FORCEON. Nevertheless, if strictly manual control over powerdown is desired, the user must strap FORCEON high to disable the automatic powerdown circuitry.

Connecting  $\overline{\text{FORCEOFF}}$  and FORCEON together disables the automatic powerdown feature, enabling them to function as a manual SHUTDOWN input (see Figure 4).

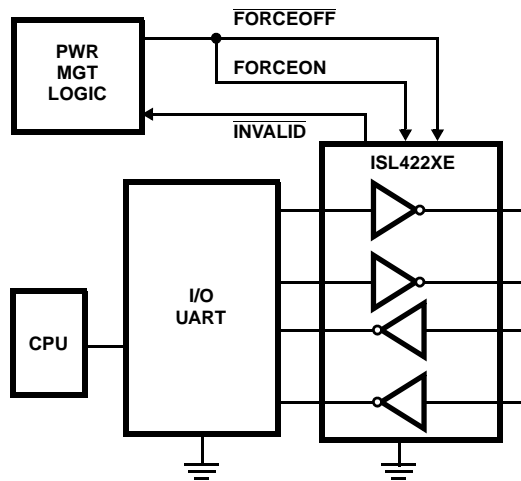


FIGURE 4. CONNECTIONS FOR MANUAL POWERDOWN WHEN NO VALID RECEIVER SIGNALS ARE PRESENT

The time to recover from automatic powerdown mode is typically 100 $\mu$ s.

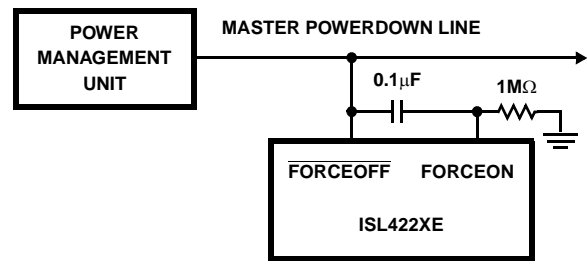


FIGURE 5. CIRCUIT TO PREVENT AUTO POWERDOWN FOR 100ms AFTER FORCED POWERUP

**Automatic Powerdown**

Even greater power savings is available by using the automatic powerdown function. When no valid RS-232 voltages (see Figure 6) are sensed on any receiver input for 30 $\mu$ s, the charge pump and transmitters powerdown, thereby reducing supply current to 10nA. Invalid receiver levels occur whenever the driving peripheral's outputs are shut off (powered down) or when the RS-232 interface cable is disconnected. The ISL422XE powers back up whenever it detects a valid RS-232 voltage level on any receiver input. This automatic powerdown feature provides additional system power savings without changes to the existing operating system.

Automatic powerdown operates when the FORCEON input is low, and the  $\overline{\text{FORCEOFF}}$  input is high. Tying FORCEON high disables automatic powerdown, but manual powerdown is always available via the overriding  $\overline{\text{FORCEOFF}}$  input. Table 2 summarizes the automatic powerdown functionality.

Some applications may need more time to wake up from shutdown. If automatic powerdown is being utilized, the RS-232 device will reenter powerdown if valid receiver levels aren't reestablished within 30 $\mu$ s of the ISL422XE powering up. Figure 5 illustrates a circuit that keeps the ISL422XE



from initiating automatic powerdown for 100ms after powering up. This gives the slow-to-wake peripheral circuit time to reestablish valid RS-232 output levels.

The time to recover from automatic powerdown mode is typically 100 $\mu$ s.

**INVALID Output**

The  $\overline{\text{INVALID}}$  output always indicates whether or not a valid RS-232 signal (see Figure 6) is present at any of the receiver inputs (see Table 2), giving the user an easy way to determine when the interface block should power down. Invalid receiver levels occur whenever the driving peripheral's outputs are shut off (powered down) or when the RS-232 interface cable is disconnected. In the case of a disconnected interface cable where all the receiver inputs are floating (but pulled to GND by the internal receiver pull down resistors), the  $\overline{\text{INVALID}}$  logic detects the invalid levels and drives the output low. The power management logic then uses this indicator to power down the interface block. Reconnecting the cable restores valid levels at the receiver inputs,  $\overline{\text{INVALID}}$  switches high, and the power management logic wakes up the interface block.  $\overline{\text{INVALID}}$  can also be used to indicate the DTR or RING INDICATOR signal, as long as the other receiver inputs are floating, or driven to GND (as in the case of a powered down driver).

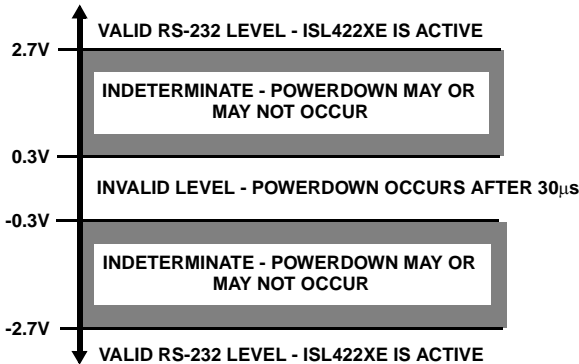


FIGURE 6. DEFINITION OF VALID RS-232 RECEIVER LEVELS

$\overline{\text{INVALID}}$  switches low after invalid levels have persisted on all of the receiver inputs for more than 30 $\mu$ s (see Figure 7).  $\overline{\text{INVALID}}$  switches back high 1 $\mu$ s after detecting a valid RS-232 level on a receiver input.  $\overline{\text{INVALID}}$  operates in all modes (forced or automatic powerdown, or forced on), so it is also useful for systems employing manual powerdown

circuitry. When automatic powerdown is utilized,  $\overline{\text{INVALID}} = 0$  indicates that the ISL422XE is in powerdown mode.

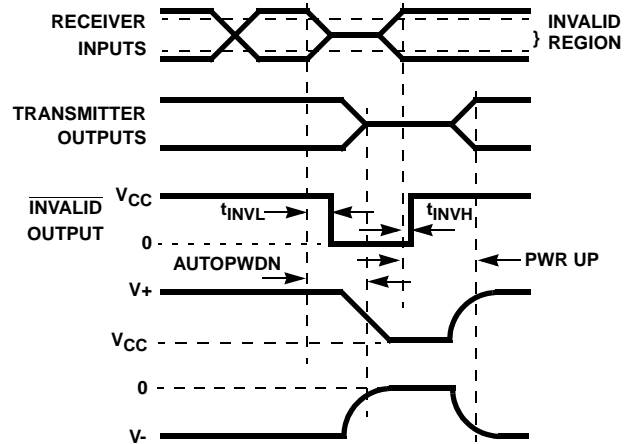


FIGURE 7. AUTOMATIC POWERDOWN AND  $\overline{\text{INVALID}}$  TIMING DIAGRAMS

**Capacitor Selection**

The charge pumps require 0.1 $\mu$ F, or greater, capacitors for proper operation. Increasing the capacitor values (by a factor of 2) reduces ripple on the transmitter outputs and slightly reduces power consumption.

When using minimum required capacitor values, make sure that capacitor values do not degrade excessively with temperature. If in doubt, use capacitors with a larger nominal value. The capacitor's equivalent series resistance (ESR) usually rises at low temperatures and it influences the amount of ripple on V+ and V-.

**Power Supply Decoupling**

In most circumstances a 0.1 $\mu$ F bypass capacitor is adequate. In applications that are particularly sensitive to power supply noise, decouple V<sub>CC</sub> to ground with a capacitor of the same value as the charge-pump capacitor C<sub>1</sub>. Connect the bypass capacitor as close as possible to the IC.

**Transmitter Outputs when Exiting Powerdown**

Figure 8 shows the response of two transmitter outputs when exiting powerdown mode. As they activate, the two transmitter outputs properly go to opposite RS-232 levels, with no glitching, ringing, nor undesirable transients. Each transmitter is loaded with 3k $\Omega$  in parallel with 2500pF.



Note that the transmitters enable only when the magnitude of the supplies exceed approximately 3V.

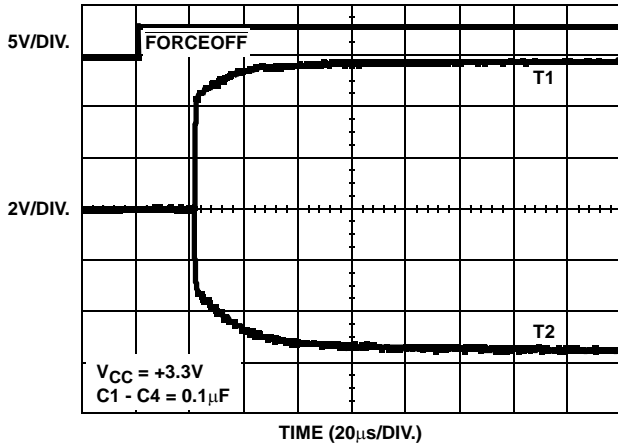


FIGURE 8. TRANSMITTER OUTPUTS WHEN EXITING POWERDOWN

### Operation Down to 2.7V

ISL422XE transmitter outputs meet RS-562 levels ( $\pm 3.7V$ ), at the full data rate, with  $V_{CC}$  as low as 2.7V. RS-562 levels typically ensure interoperability with RS-232 devices.

### High Data Rates

The ISL422XE maintain the RS-232  $\pm 5V$  minimum transmitter output voltages even at high data rates. Figure 9 details a transmitter loopback test circuit, and Figure 10 illustrates the loopback test result at 120kBps. For this test, all transmitters were simultaneously driving RS-232 loads in parallel with 1000pF, at 120kBps. Figure 11 shows the loopback results for a single transmitter driving 1000pF and an RS-232 load at 250kBps. The static transmitters were also loaded with an RS-232 receiver.

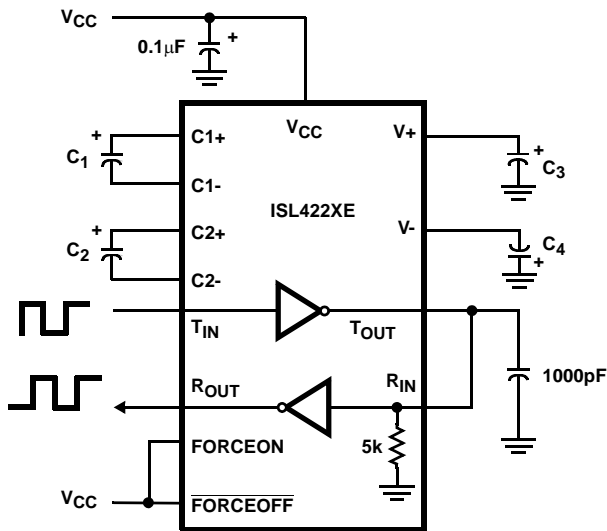


FIGURE 9. TRANSMITTER LOOPBACK TEST CIRCUIT

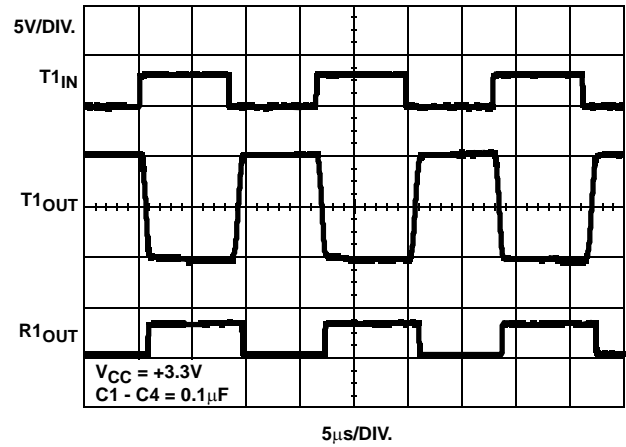


FIGURE 10. LOOPBACK TEST AT 120kBps

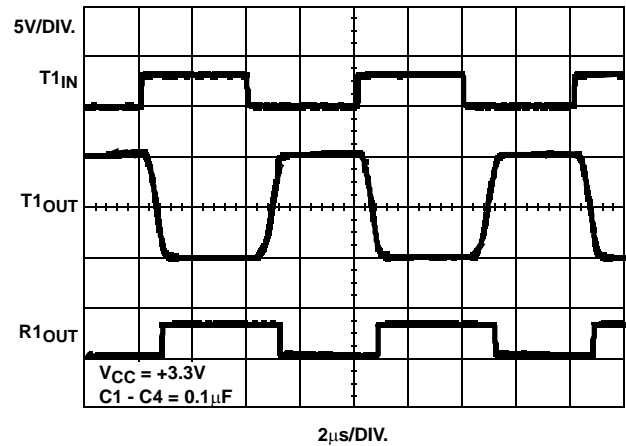


FIGURE 11. LOOPBACK TEST AT 250kBps

### Interconnection with 3V and 5V Logic

The ISL422XE directly interface with 5V CMOS and TTL logic families. Nevertheless, with the ISL422XE at 3.3V, and the logic supply at 5V, AC, HC, and CD4000 outputs can drive ISL422XE inputs, but ISL422XE outputs do not reach the minimum  $V_{IH}$  for these logic families. See Table 3 for more information.

TABLE 3. LOGIC FAMILY COMPATIBILITY WITH VARIOUS SUPPLY VOLTAGES

SYSTEM POWER-SUPPLY VOLTAGE (V)	$V_{CC}$ SUPPLY VOLTAGE (V)	COMPATIBILITY
3.3	3.3	Compatible with all CMOS families.
5	5	Compatible with all TTL and CMOS logic families.
5	3.3	Compatible with ACT and HCT CMOS, and with TTL. ISL422XE outputs are incompatible with AC, HC, and CD4000 CMOS inputs.

### ***±15kV ESD Protection***

All pins on ISL422XE devices include ESD protection structures, but the RS-232 pins (transmitter outputs and receiver inputs) incorporate advanced structures which allow them to survive ESD events up to ±15kV. The RS-232 pins are particularly vulnerable to ESD damage because they typically connect to an exposed port on the exterior of the finished product. Simply touching the port pins, or connecting a cable, can cause an ESD event that might destroy unprotected ICs. These new ESD structures protect the device whether or not it is powered up, protect without allowing any latchup mechanism to activate, and don't interfere with RS-232 signals as large as ±25V.

### ***Human Body Model (HBM) Testing***

As the name implies, this test method emulates the ESD event delivered to an IC during human handling. The tester delivers the charge through a 1.5kΩ current limiting resistor, making the test less severe than the IEC61000 test which utilizes a 330Ω limiting resistor. The HBM method determines an IC's ability to withstand the ESD transients typically present during handling and manufacturing. Due to the random nature of these events, each pin is tested with respect to all other pins. The RS-232 pins on "E" family devices can withstand HBM ESD events to ±15kV.

### ***IEC61000-4-2 Testing***

The IEC61000 test method applies to finished equipment, rather than to an individual IC. Therefore, the pins most likely to suffer an ESD event are those that are exposed to the outside world (the RS-232 pins in this case), and the IC is tested in its typical application configuration (power applied) rather than testing each pin-to-pin combination. The lower current limiting resistor coupled with the larger charge storage capacitor yields a test that is much more severe than the HBM test. The extra ESD protection built into this device's RS-232 pins allows the design of equipment meeting level 4 criteria without the need for additional board level protection on the RS-232 port.

### **AIR-GAP DISCHARGE TEST METHOD**

For this test method, a charged probe tip moves toward the IC pin until the voltage arcs to it. The current waveform delivered to the IC pin depends on approach speed, humidity, temperature, etc., so it is difficult to obtain repeatable results. The "E" device RS-232 pins withstand ±15kV air-gap discharges.

### **CONTACT DISCHARGE TEST METHOD**

During the contact discharge test, the probe contacts the tested pin before the probe tip is energized, thereby eliminating the variables associated with the air-gap discharge. The result is a more repeatable and predictable test, but equipment limits prevent testing devices at voltages higher than ±8kV. All "E" family devices survive ±8kV contact discharges on the RS-232 pins.

Typical Performance Curves  $V_{CC} = 3.3V, T_A = 25^\circ C$

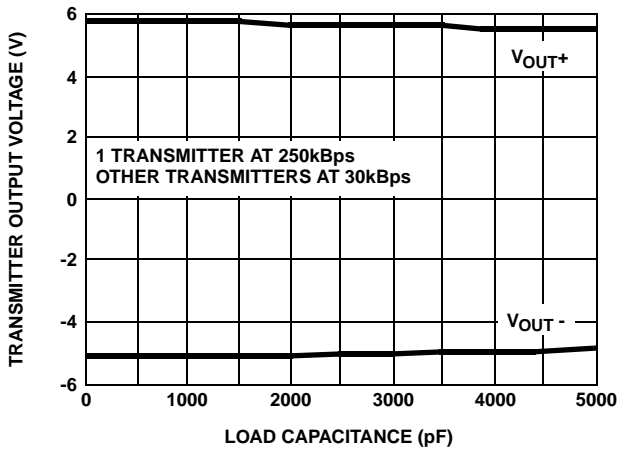


FIGURE 12. TRANSMITTER OUTPUT VOLTAGE vs LOAD CAPACITANCE

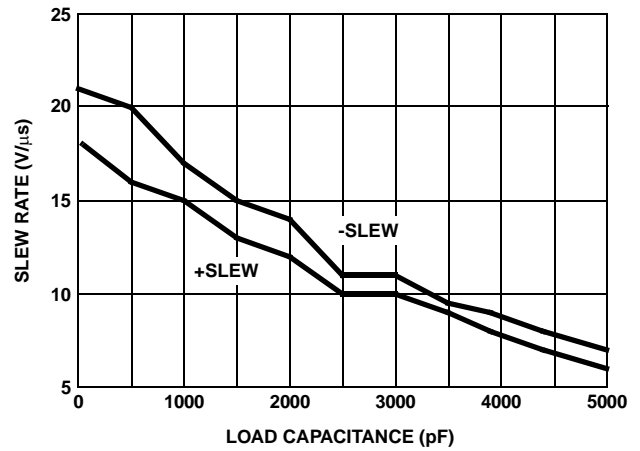


FIGURE 13. SLEW RATE vs LOAD CAPACITANCE

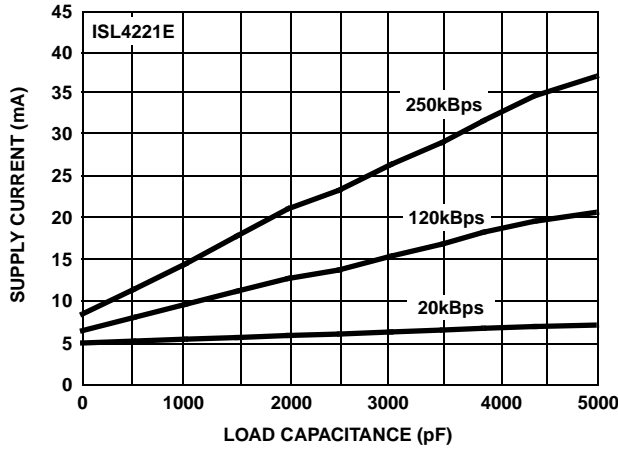


FIGURE 14. SUPPLY CURRENT vs LOAD CAPACITANCE WHEN TRANSMITTING DATA

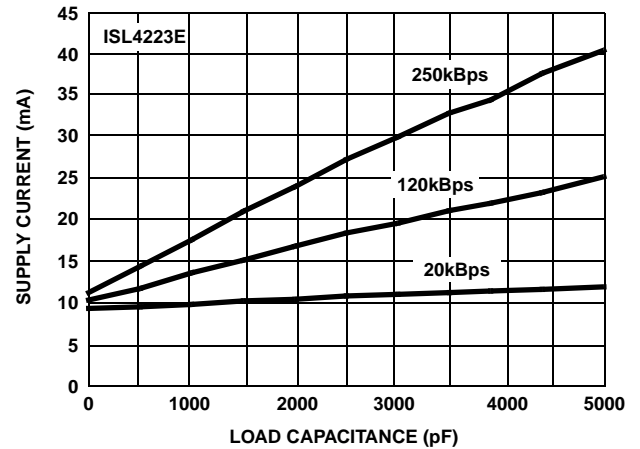


FIGURE 15. SUPPLY CURRENT vs LOAD CAPACITANCE WHEN TRANSMITTING DATA

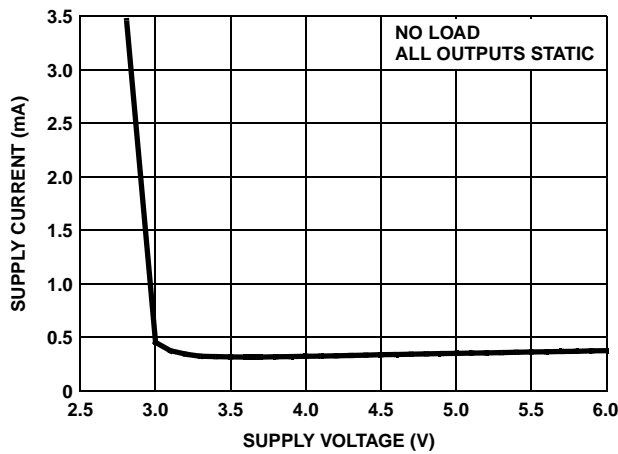


FIGURE 16. SUPPLY CURRENT vs SUPPLY VOLTAGE

**Die Characteristics**

**SUBSTRATE POTENTIAL (POWERED UP):**

GND

**TRANSISTOR COUNT:**

ISL4221E: 286

ISL4223E: 357

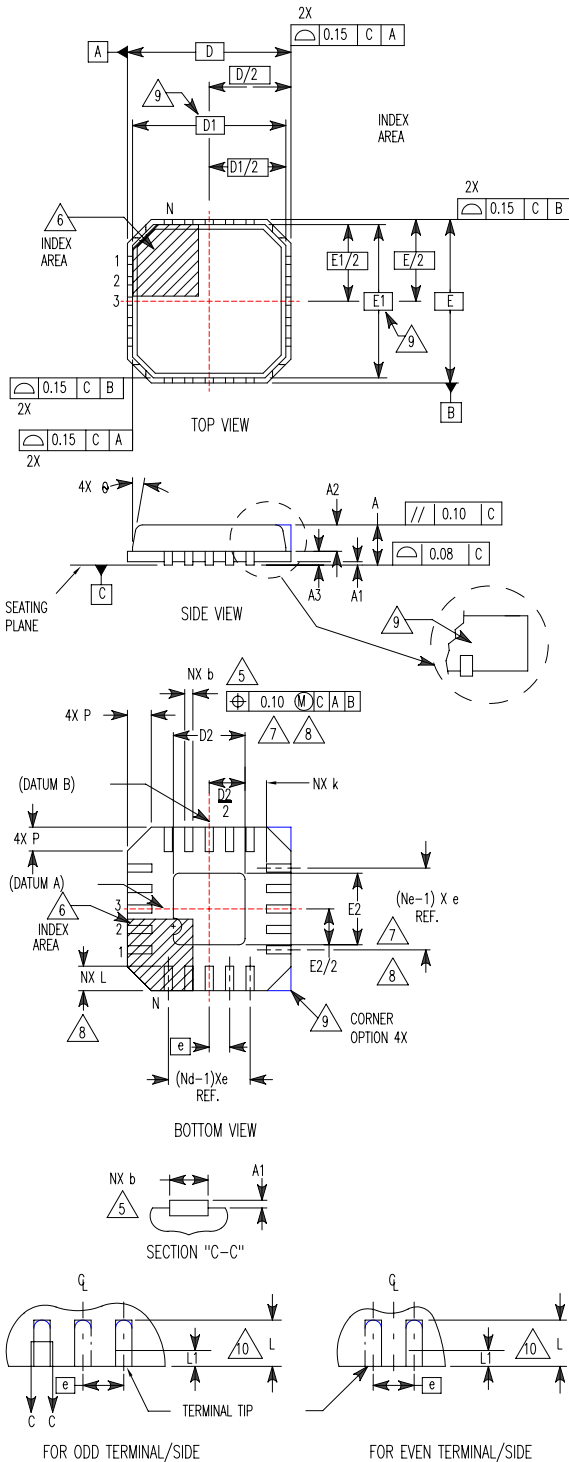
**PROCESS:**

Si Gate CMOS

**Quad Flat No-Lead Plastic Package (QFN)  
Micro Lead Frame Plastic Package (MLFP)**

**L16.5x5**

16 LEAD QUAD FLAT NO-LEAD PLASTIC PACKAGE  
(COMPLIANT TO JEDEC MO-220VHHB ISSUE C)



SYMBOL	MILLIMETERS			NOTES
	MIN	NOMINAL	MAX	
A	0.80	0.90	1.00	-
A1	-	-	0.05	-
A2	-	-	1.00	9
A3	0.20 REF			9
b	0.28	0.33	0.40	5, 8
D	5.00 BSC			-
D1	4.75 BSC			9
D2	2.55	2.70	2.85	7, 8
E	5.00 BSC			-
E1	4.75 BSC			9
E2	2.55	2.70	2.85	7, 8
e	0.80 BSC			-
k	0.25	-	-	-
L	0.35	0.60	0.75	8
L1	-	-	0.15	10
N	16			2
Nd	4			3
Ne	4	4		3
P	-	-	0.60	9
theta	-	-	12	9

Rev. 2 10/02

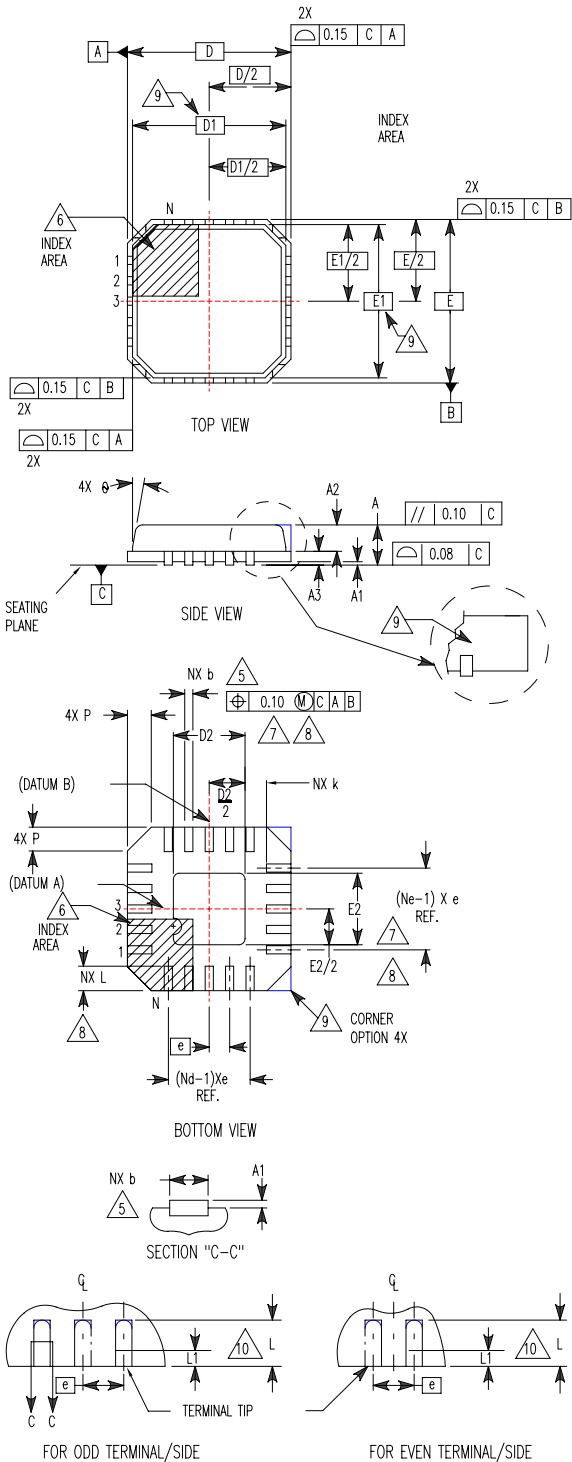
**NOTES:**

1. Dimensioning and tolerancing conform to ASME Y14.5-1994.
2. N is the number of terminals.
3. Nd and Ne refer to the number of terminals on each D and E.
4. All dimensions are in millimeters. Angles are in degrees.
5. Dimension b applies to the metallized terminal and is measured between 0.15mm and 0.30mm from the terminal tip.
6. The configuration of the pin #1 identifier is optional, but must be located within the zone indicated. The pin #1 identifier may be either a mold or mark feature.
7. Dimensions D2 and E2 are for the exposed pads which provide improved electrical and thermal performance.
8. Nominal dimensions are provided to assist with PCB Land Pattern Design efforts, see Intersil Technical Brief TB389.
9. Features and dimensions A2, A3, D1, E1, P & theta are present when Anvil singulation method is used and not present for saw singulation.
10. Depending on the method of lead termination at the edge of the package, a maximum 0.15mm pull back (L1) maybe present. L minus L1 to be equal to or greater than 0.3mm.

**Quad Flat No-Lead Plastic Package (QFN)  
Micro Lead Frame Plastic Package (MLFP)**

**L20.5x5**

20 LEAD QUAD FLAT NO-LEAD PLASTIC PACKAGE  
(COMPLIANT TO JEDEC MO-220VHHC ISSUE C)



SYMBOL	MILLIMETERS			NOTES
	MIN	NOMINAL	MAX	
A	0.80	0.90	1.00	-
A1	-	-	0.05	-
A2	-	-	1.00	9
A3	0.20 REF			9
b	0.23	0.28	0.38	5, 8
D	5.00 BSC			-
D1	4.75 BSC			9
D2	2.95	3.10	3.25	7, 8
E	5.00 BSC			-
E1	4.75 BSC			9
E2	2.95	3.10	3.25	7, 8
e	0.65 BSC			-
k	0.25	-	-	-
L	0.35	0.60	0.75	8
L1	-	-	0.15	10
N	20			2
Nd	5			3
Ne	5			3
P	-	-	0.60	9
θ	-	-	12	9

Rev. 3 10/02

**NOTES:**

1. Dimensioning and tolerancing conform to ASME Y14.5-1994.
2. N is the number of terminals.
3. Nd and Ne refer to the number of terminals on each D and E.
4. All dimensions are in millimeters. Angles are in degrees.
5. Dimension b applies to the metallized terminal and is measured between 0.15mm and 0.30mm from the terminal tip.
6. The configuration of the pin #1 identifier is optional, but must be located within the zone indicated. The pin #1 identifier may be either a mold or mark feature.
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9. Features and dimensions A2, A3, D1, E1, P & θ are present when Anvil singulation method is used and not present for saw singulation.
10. Depending on the method of lead termination at the edge of the package, a maximum 0.15mm pull back (L1) maybe present. L minus L1 to be equal to or greater than 0.3mm.

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